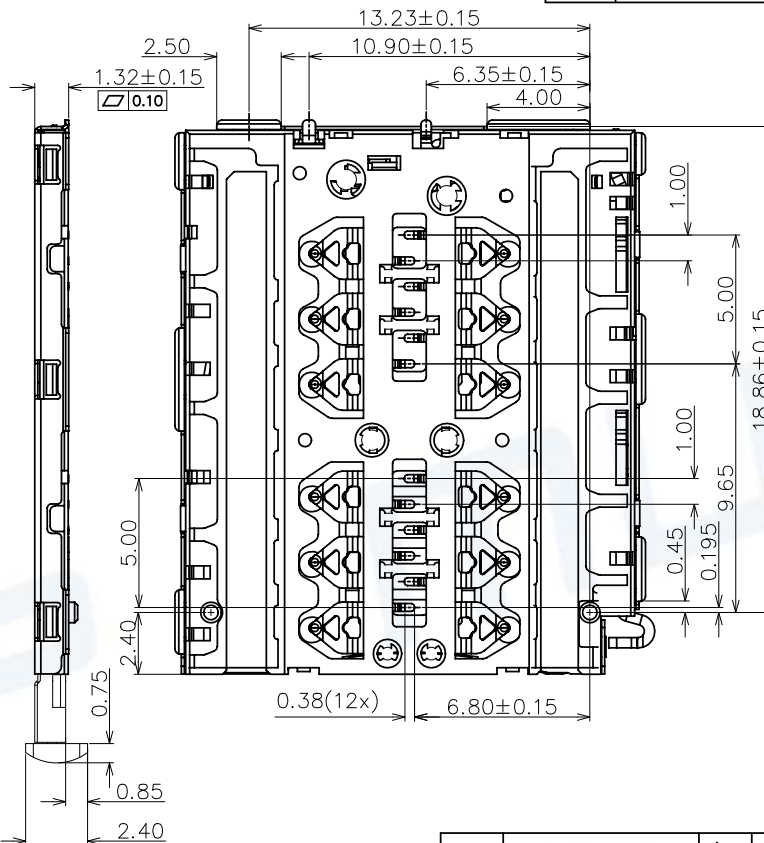
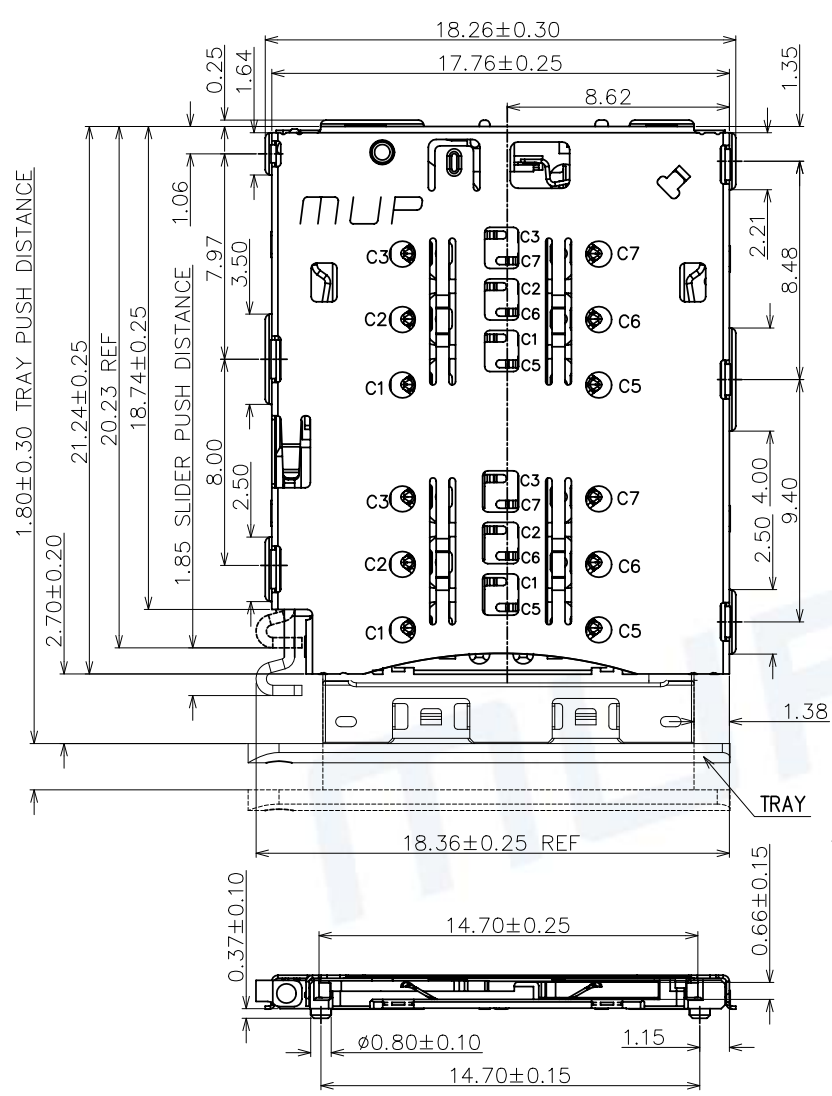


REV.	DESCRIPTION OF REVISIONS	APPR.	DRAW.	RELEASE	DATE
1	NEW REVISION				Henry Nov.14.2018
2					



TECHNICAL CHARACTERISTICS

1.General Characteristics
 Dimensions:21.24LX17.76WX1.35H mm
 TRAY MATING FORCE:1~10N
 TRAY UNMATING FORCE:2~10N
 Durability:1,500 cycles min.

2.Electrical Characteristics
 Contact resistance:50mΩ typical,
 100mΩMax
 Insulation resistance:>1000MΩ/500V DC

3.Solderability
 Vaporphase:215°C, 30sec.Max
 IR reflow:250°C,5sec.Max
 Manual soldering:370°C.3sec.Max

4.Environmental Characteristics
 Operating temperature:-40°C~+85°C
 Operating humidity:10%~+95%RH

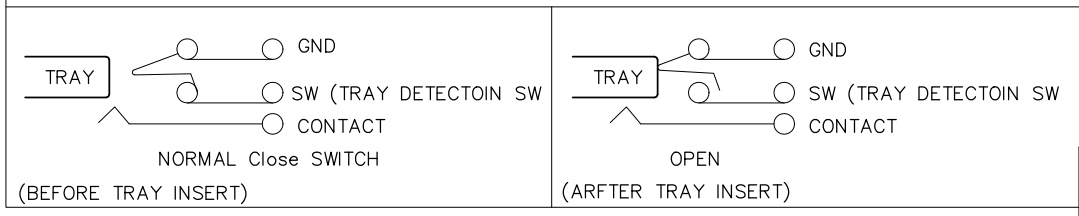
ITEM	PART NAME	Q'TY	MATERIAL	FINISH
1	HOUSING	1	Hi-temp Thermoplastic	Black UL94V-0
2	DATA CONTACT	12	Copper Alloy	Contact area:Gold plated
3	SWITCH	1	Copper Alloy	Contact area:Gold plated
4	SHELL	1	Stainless Steel	Solder area:Gold plated
5	RODKER	1	Stainless Steel	
6	LATCH	2	Stainless Steel	
7	LEVER-BAR	1	Stainless Steel	

Unless otherwise specified, other tolerance are:

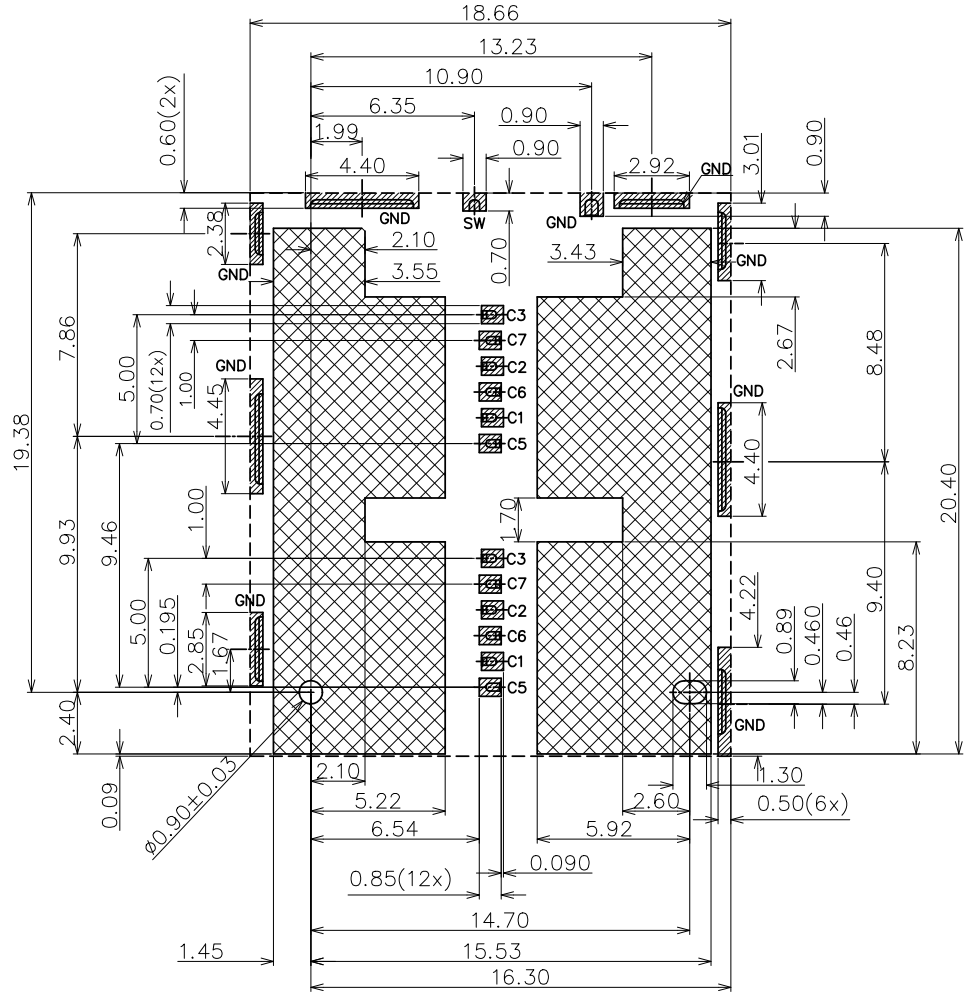
MUP MUP INDUSTRIAL CO.,LTD.

X ±0.35	X* ±5°	NAME: DUAL NANO-SIM Card Connector
X.X ±0.25	X.X* ±4°	MODEL NO: MUP-C787-1
X.XX ±0.15	X.XX* ±3°	TYPE : H1.35mm Normally Colse With Card Tray Type
X.XXX ±0.10	X.XXX* ±2°	PROJ. UNIT mm SCALE 1:1
CUSTOMER DRAWING		DRAWN Henry Nov.14.2018 DWG NO.: DWG-MUP-C787-1
		CHECKED Henry Nov.14.2018 SHEET 1/2 REVISION 1
		APPROVAL Simon Nov.14.2018

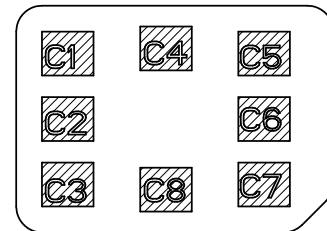
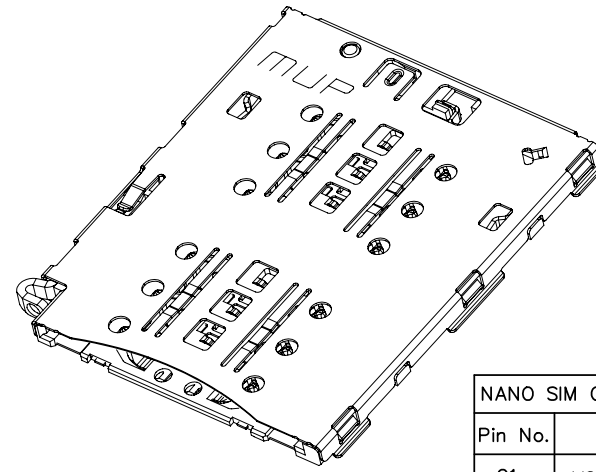
CIRCUIT DIAGRAM FOR DETECT SWITCHES



REV.	DESCRIPTION OF REVISIONS	APPR.	DRAW.	RELEASE	DATE
1	NEW REVISION				Henry Nov.14.2018
2					



RECOMMENDED P.C.B LAYOUT
 COMPONENT SIDE(TOLERANCE ±0.05)
 ▨ PAD AREA
 ▤ KEEP AREA
 ▩ NO PATTERN AND VIA HOLE IN THIS AREA



NANO SIM CAED

NANO SIM CARD	
Pin No.	ASSIGNMENT
C1	VCC(SUPPLY VOLTAGE)
C2	RST(RESET SIGNAL)
C3	CLK(CLOCK SIGNAL)
SW	DETECTION SWITCH
GND	GND
C5	GND
C6	VPP(VARIABLE SUPPLY VOLTAGE)
C7	I/O(DATA INPUT/OUTPUT)

ITEM	PART NAME	Q'TY	MATERIAL	FINISH
1	HOUSING	1	Hi-temp Thermoplastic	Black UL94V-0
2	DATA CONTACT	12	Copper Alloy	Contact area:Gold plated
3	SWITCH	1	Copper Alloy	Contact area:Gold plated
4	SHELL	1	Stainless Steel	Solder area:Gold plated
5	RODKER	1	Stainless Steel	
6	LATCH	2	Stainless Steel	
7	LEVER-BAR	1	Stainless Steel	

Unless otherwise specified, other tolerance are:

X ±0.35	X* ±5°	NAME: DUAL NANO-SIM Card Connector
X.X ±0.25	X.X* ±4°	
X.XX ±0.15	X.XX* ±3°	
X.XXX ±0.10	X.XXX* ±2°	

MUP MUP INDUSTRIAL CO.,LTD.

MODEL NO: **MUP-C787-1**

TYPE : **H1.35mm Normally Colse With Card Tray Type**

PROJ.	UNIT	SCALE	DRAWN	DWG NO.:
①	mm	1:1	Henry Nov.14.2018	DWG-MUP-C787-1
CUSTOMER DRAWING			CHECKED	SHEET
			Simon Nov.14.2018	2/2
			APPROVAL	REVISION
				1



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